FutureHorizons

The Global Semiconductor Industry Analysts

FH MONDAY

25 October 2021



Future Horizons Ltd, • 44 Bethel Road • Sevenoaks • Kent TN13 3UE • England Tel: +44 1732 740440 • Fax: +44 1732 740442 e-mail: <u>mail@futurehorizons.com</u>• <u>http://www.futurehorizons.com/</u> Affiliates in Europe, India, Israel, Japan, Russian, San Jose California, USA

Growing IoT Sector Bodes Well for Bluetooth Industry

India's Internet of Things (IoT) investments are expected to reach \$15 billion this year, up from \$5 billion in 2019, according to a report by global management and strategy consulting firm Zinnov. The study highlights that India had 200–250 million connected devices by the end of 2019. This is projected to grow tenfold to touch 2 billion devices by 2021, mainly driven by the manufacturing, automotive and transportation, and energy and utilities sectors.

IoT adoption in India has exploded in the last three years, with enterprises spending billions of dollars in testing and deploying several IoT use cases. According to Zinnov, five key segments are contributing to the overall IoT market demand in India—large enterprises in which IoT adoption rate is around 35%; global capability centers that are rapidly testing, implementing, and scaling IoT technologies and use cases; small and medium businesses that are leveraging some form of advanced digital technology solutions for driving business operations, including artificial intelligence (AI), cloud, and IoT; the increasing connectivity and smartphone penetration across the country that are driving the adoption of IoT-based solutions in the consumer segment; and the Government, which is driving large-scale initiatives such as the Smart Cities project and the Digital India program.

NXP Semiconductors Taps AWS for EDA in the Cloud

NXP Semiconductors has selected Amazon Web Services (AWS), an Amazon.com Inc. company, as its preferred cloud provider and is migrating the vast majority of its electronic design automation (EDA) workloads from NXP data centers to AWS.

Running on the world's leading cloud extends NXP's efficiency and competitive edge in the design and verification of advanced semiconductors tailored to the requirements of automotive, industrial Internet of Things (IoT), mobile, and communications infrastructure businesses.

The Netherlands-based company uses AWS's proven global infrastructure and capabilities in high performance computing (HPC), storage, analytics, and machine learning to enhance collaboration and EDA throughput across dozens of its worldwide design centers, as well as to reduce costs with elastic scaling of compute resources and minimize scheduling risks for design projects. In addition, thanks to AWS's virtually unlimited scale, NXP engineers gain more time to focus on innovation rather than managing compute resources.

Infineon Safeguards V2X Communication

With trends such as electrification, autonomous driving and connected cars, the number of communication interfaces in vehicles is growing – whether wired or wireless. However, this development entails new challenges because the numerous communication channels create new attack surfaces increasing the vulnerability of the systems. Comprehensive security concepts are therefore becoming more important to support safety of passengers and the protection of their data.

Infineon Technologies AG's SLS37 V2X hardware security module (HSM) is a plug-and-play security solution for vehicle to everything communication (V2X). The SLS37 V2X HSM is based on a highly secured, tamper resistant microcontroller tailored to the security needs in V2X applications within telematics control units.

TI Rolls 3D Hall Sensor for Real-Time Control

Texas Instruments has introduced TMAG5170, the first device in a new family of 3D Hall-effect position sensors for real-time control in factory automation and motor-drive applications. The sensor is promoted as providing integrated functions and diagnostics to maximize design flexibility and system safety while saving energy.

Magnetic sensors, including Hall-effect sensors and other technologies, have design benefits and drawbacks. One constraint is the trade-off between obtaining extremely high accuracy and 3D device throughput. Stable sensors, for example, do not wander in response to changes in temperature, ambient conditions or even magnetic fields. It is usually simple to enhance one of the two ways, but not both.

PragmatIC Semi Gets \$80M for Fab in UK

PragmatIC Semiconductor has secured \$80 million in funding to build a second FlexLogIC fab with five times the capacity of its existing fab, in order to meet a growing demand for its low-cost flexible integrated circuits (IC) for the internet of things (IoT).

In an interview to explain the rationale for the new fab and the company's intentions, Scott White, CEO of PragmatIC Semiconductor told EE Times, "The first fab was introduced a couple of years ago, for which demand has been good. We expect to reach capacity soon, so the new planned fab will be a larger capacity version of the existing one. The second fab will also be a template for offering a fab-on-site to customers in the future, which will be modular and low capex."